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PATENT & TRADEMARK OFFICE

PATENT
Atty. Dkt. No. AMAT/3778/CMP/CMP/RKK

AF
3700

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Chen et al.

Serial No.: 09/728,038

Confirmation No.: 2584

Filed: December 1, 2000

For: Apparatus and Method for Controlling Delivery of Slurry to a Region of a Polishing Device

Group Art Unit: 3723

Examiner: Grant, A.

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37 CFR 1.8
I hereby certify that this correspondence is being deposited on January 23, 2003 with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231.

January 23, 2003
Date

Gero G. McClellan

BOX AF
Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

RESPONSE TO FINAL OFFICE ACTION DATED OCTOBER 23, 2002

In response to the Final Office Action dated October 23, 2002, having a shortened statutory period for response set to expire on January 23, 2003, please enter this response and reconsider the claims pending in the application for reasons discussed below. The Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/3778/CMP/CMP/GGM in the amount of $84.00, or for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

IN THE CLAIMS:

1. An apparatus, comprising a semiconductor polishing device having a first surface defining at least two non-intersecting fluid retaining grooves at least a portion of which is